



# Dicing Blade Technical Seminar



## *Dicing Blade Seminar*



■ **History:**

- 4" versus 2" technology
- Separating techniques

■ **Marketing profile & Market segmentation**

■ **Manufacturing techniques:**

- Nickel Bond
- Steel core - Nickel
- Resin Bond
- Metal Sintered
- Diamond selection

■ **Blade characteristics:**

- Advantages & disadvantages of the different blade binders & blade geometry's

■ **Dressing:**

- Principles
- Dressing techniques

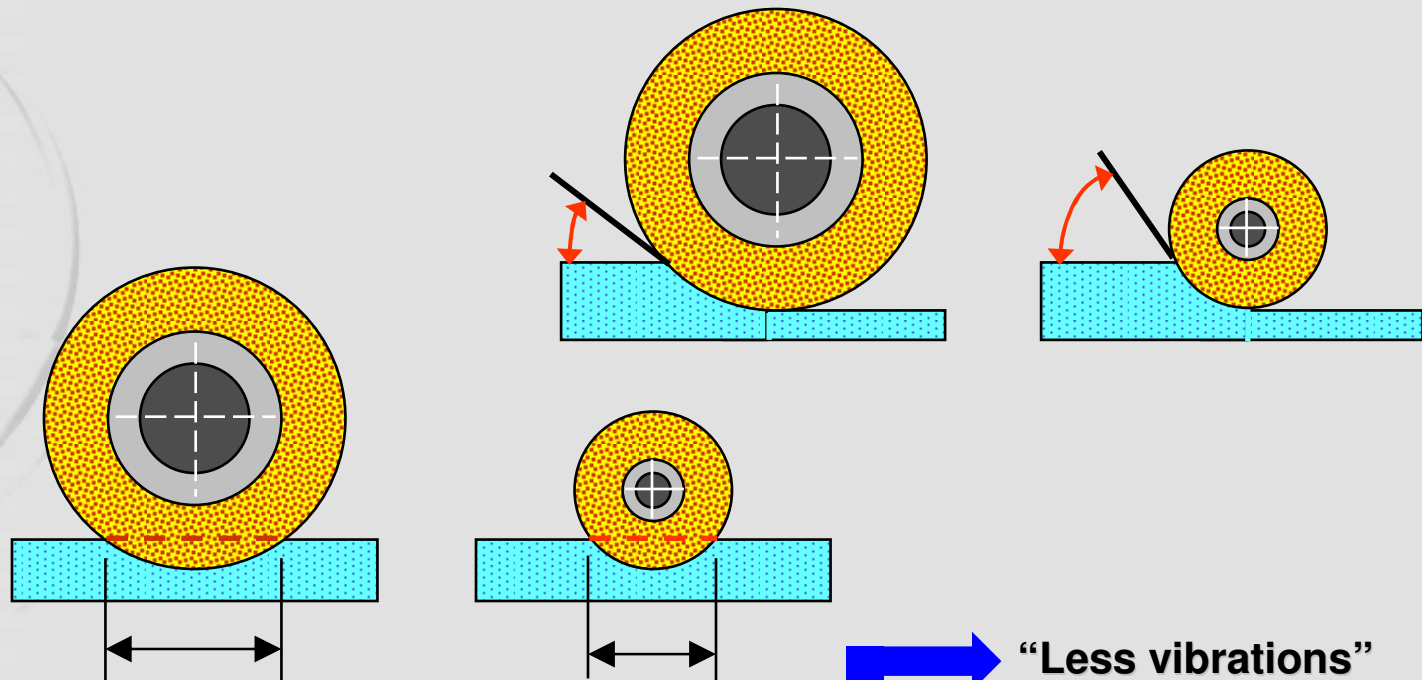


### Cont.

- **Process techniques & Parameters:**
  - Application Characteristics
  - Cutting mode
  - Clamping methods
  - Cooling
  - High cooling flange
  - Cutting through heavy substrates
  - Cutting through into tapes
  - Recommended exposure left
  
- **Major applications - Material dicing guide:**
  - Recommended Spindle speed
  - Dicing green ceramic
  
- **Special applications:**
  
- **Optimizing the cutting process:**
  
- **Trouble shooting:**

## 4" Diameter Versus 2" Diameter

**More edge surface** → **Longer life { Less blade wear }**  
**{ More diamonds }**  
**Shallower angle of attack** → **Less material damage**



**More blade surface in kerf during dicing**

→ **"Less vibrations"**  
→ **"Higher feed rate"**



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## *Dicing Blade Seminar*

**K&S - 775**





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## *Dicing Blade Seminar*

**K&S - 780**





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## *Dicing Blade Seminar*

**K&S - 980**







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## Dicing Blade Seminar

**ADT - 7100**





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## *Dicing Blade Seminar*

**ADT  
7500 & 7300**





## *Dicing Blade Seminar*

**ADT - 7200**

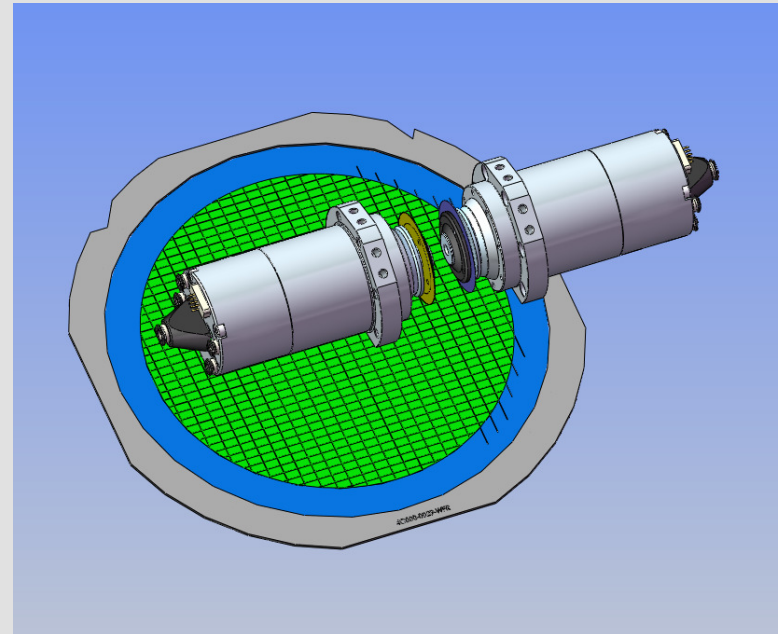




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ADT - 7900



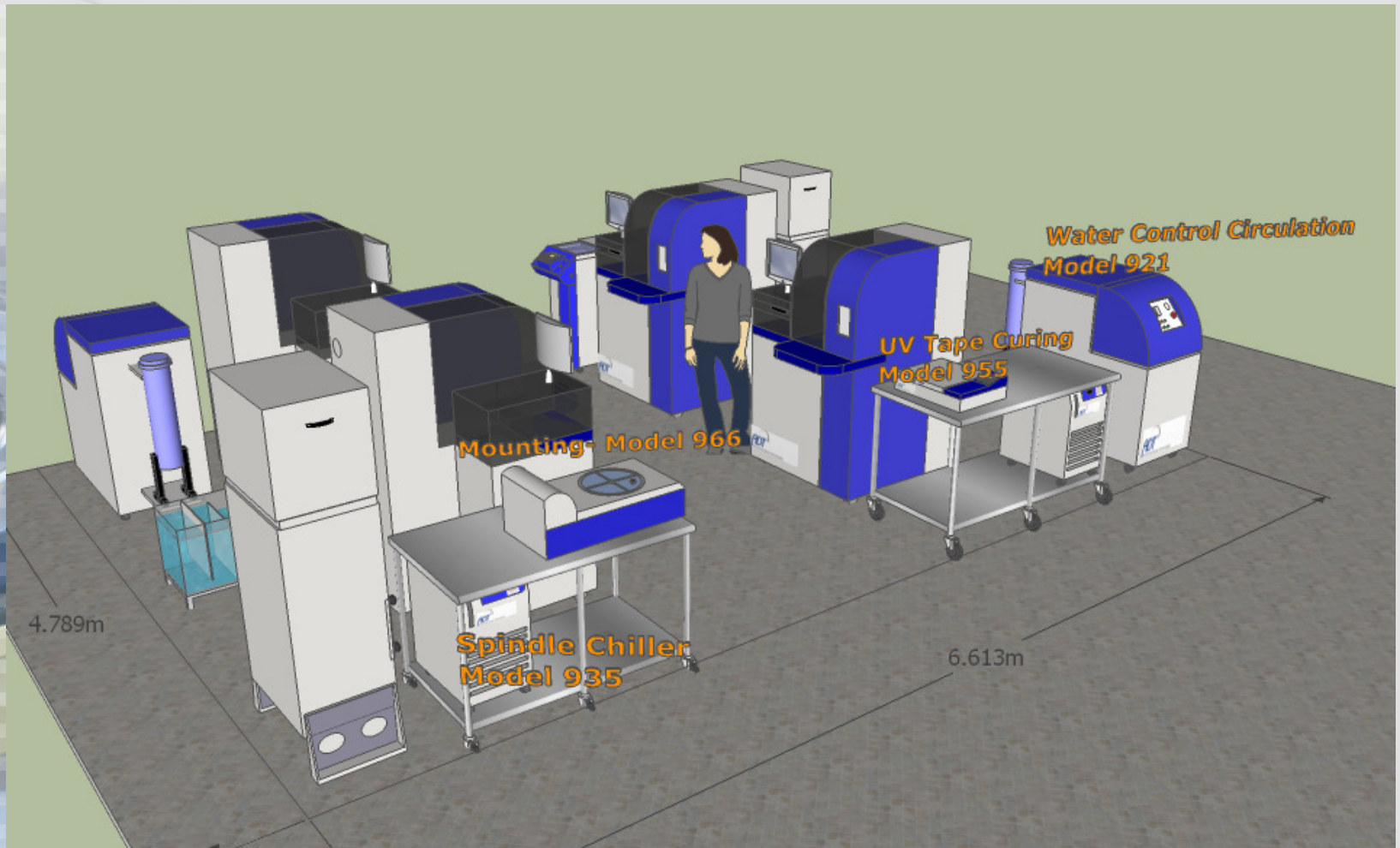
## Peripheral Products

- ❑ **966 - Wafer Mounting Stations**
- ❑ **955 - UV Curing Systems**
- ❑ **977 - Wafer Cleaning Stations**
- ❑ **937 - Re Circulating Spindle Water Chiller**
- ❑ **921 - Closed Loop Filtration System**
- ❑ **947 - CO<sub>2</sub> In-Line injector**
- ❑ **Film Frames and Film Frame Cassettes**

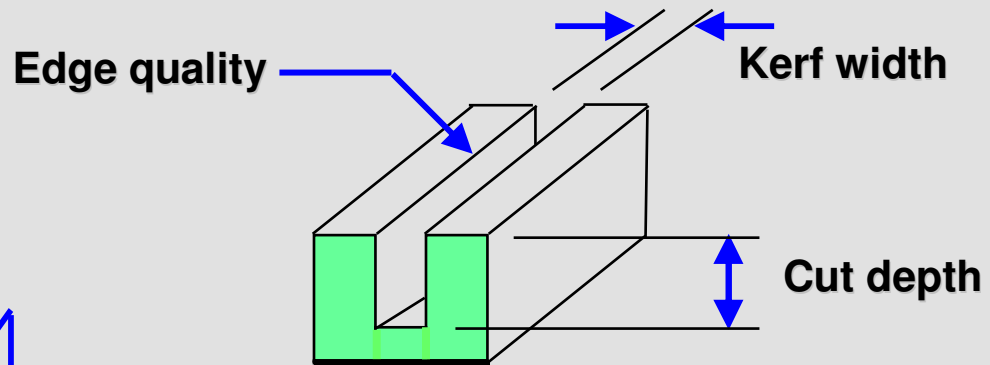




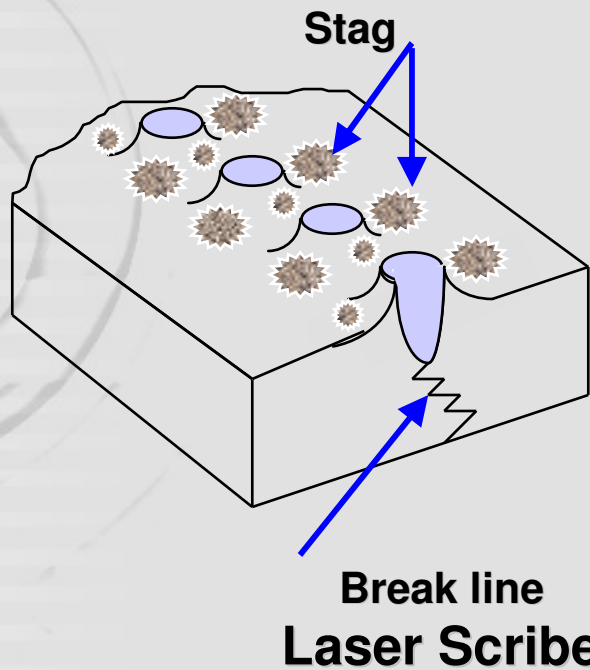
# Peripheral Products



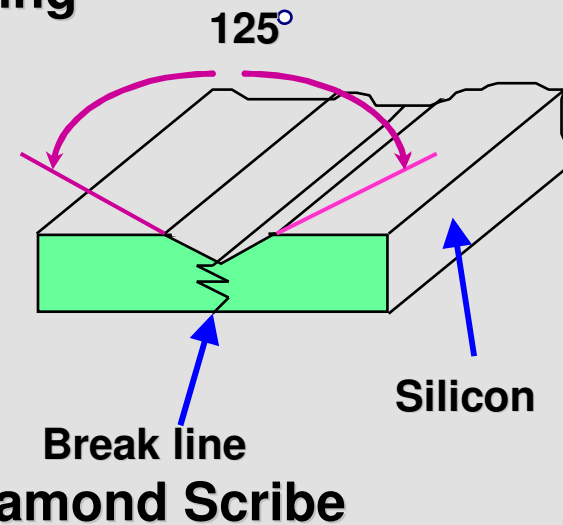
## Separating Techniques



**Diamond dicing**

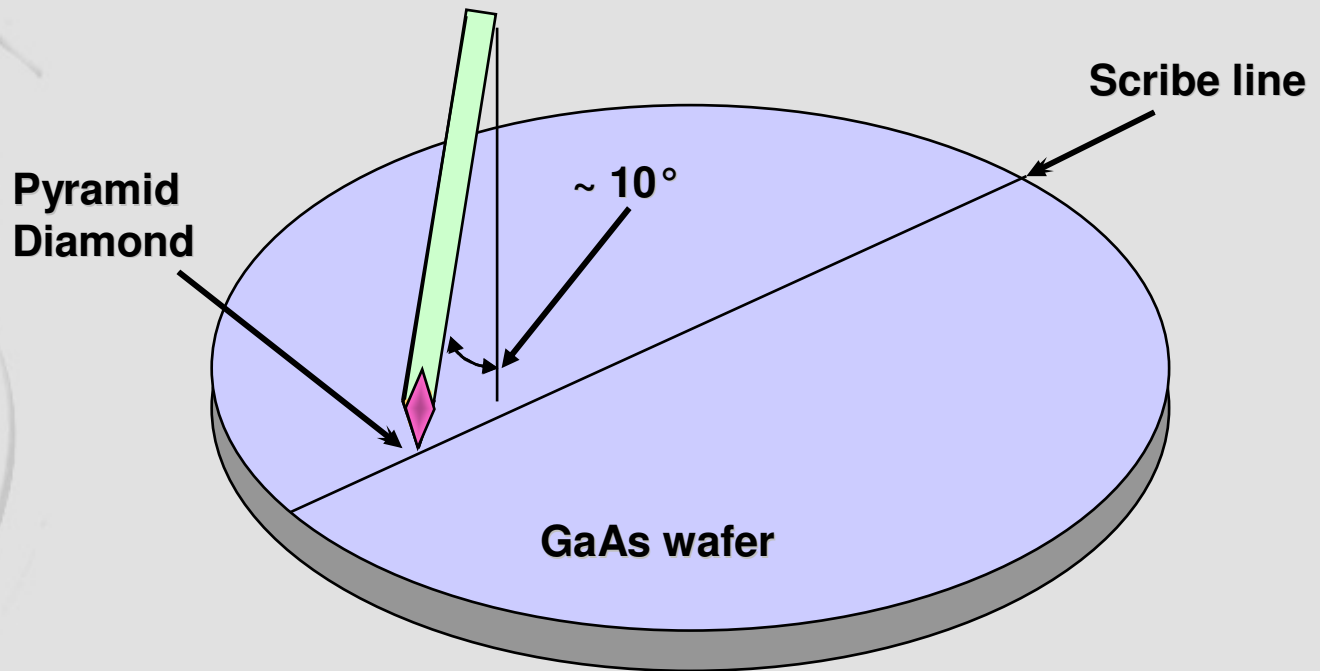


**Laser Scribe**

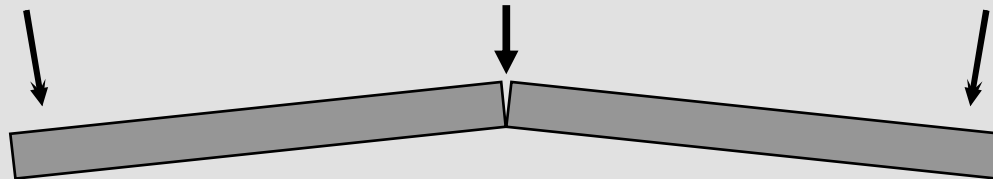


**Diamond Scribe**

## Diamond Scribing process

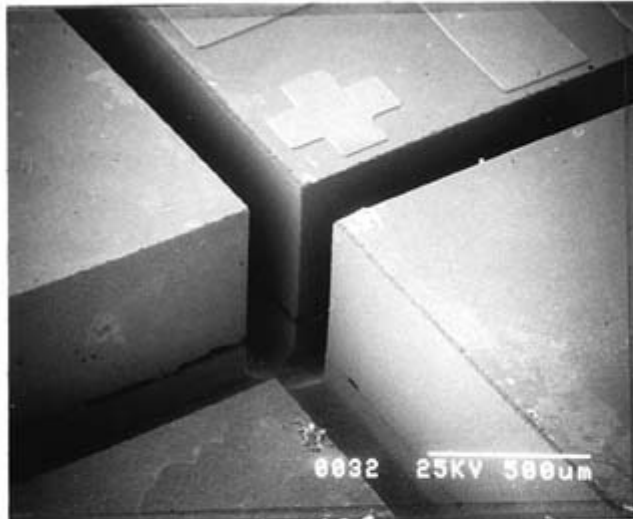


Scribe & break line

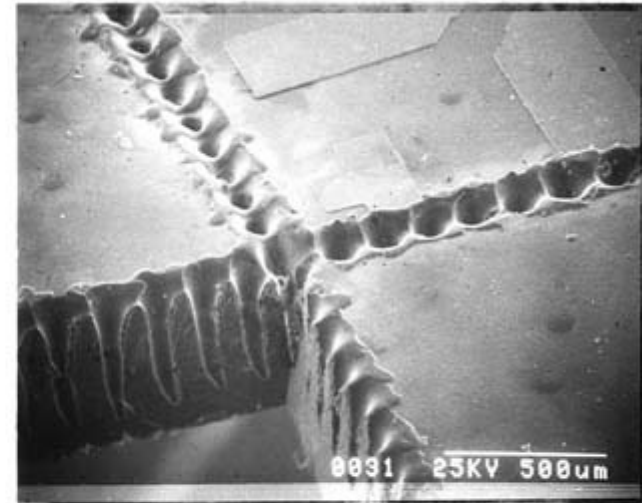




## *Separating Techniques*



HARD AL. SUBSTRATE DICED  
WITH A DIAMOND RESINOID BLADE  
ON THE K+S 784 SAW.



HARD AL. SUBSTRATE SCRIBED  
WITH A LASER BEAM.



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# Marketing Profile & Market Segmentation



## *Market Profile*

**Instrumentation**  
**Optoelectronics & Optics**  
**Sensors & Transducers**

**Data Processing**  
**Magnetic Heads**

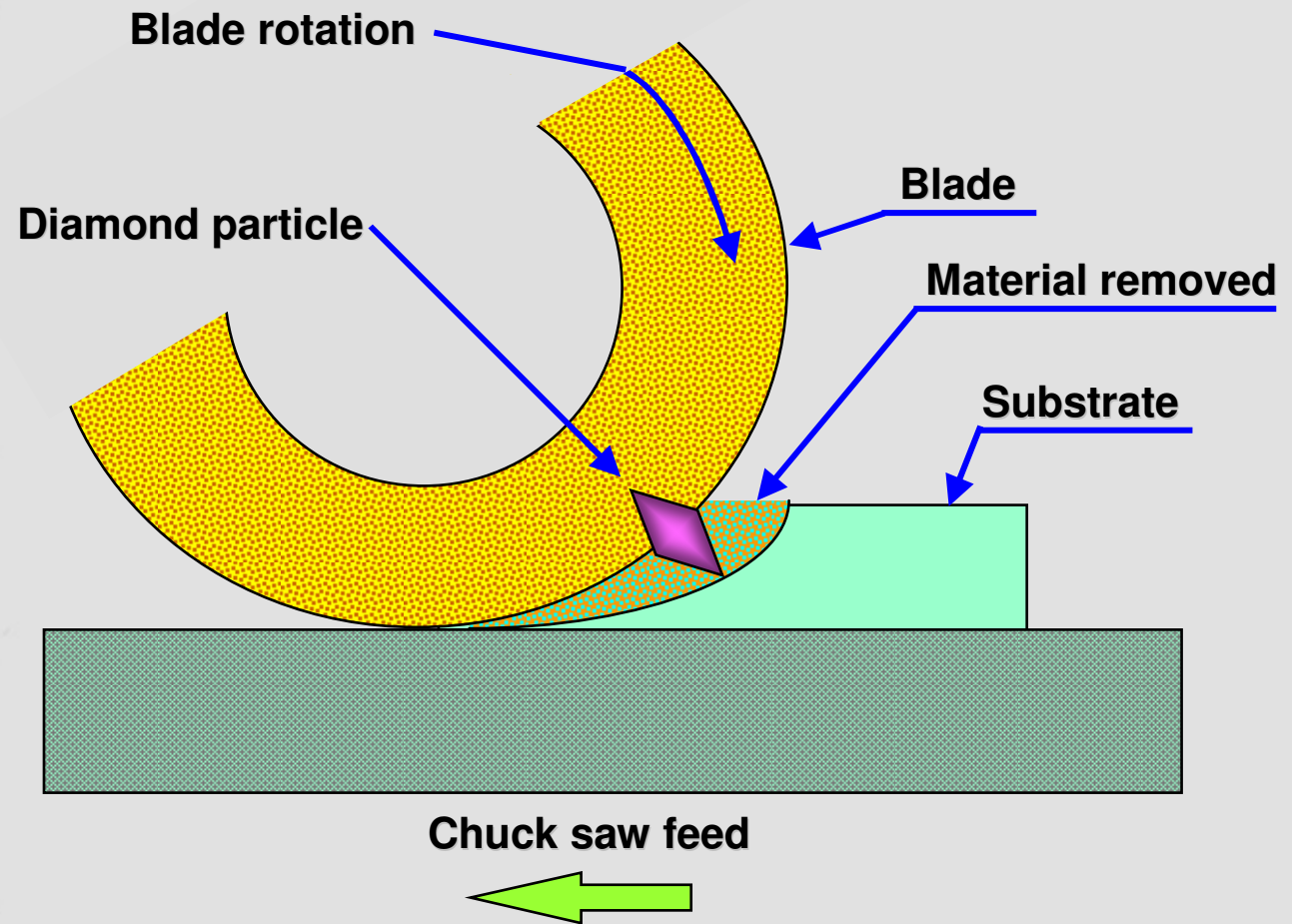
**Precision  
Dicing  
Systems**

**Electronics**  
**Active Devices**  
**Passive devices**  
**Packaging**

# Market Segmentation

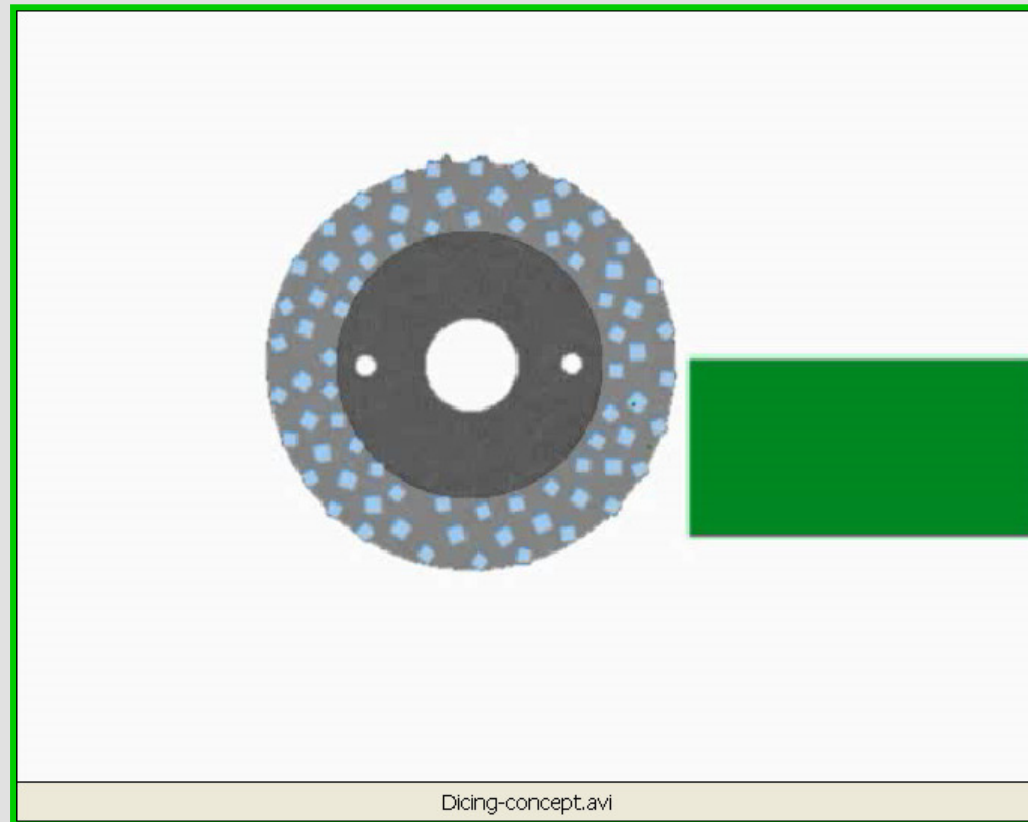
<b>Market</b>	<b>Instrumentation</b>		<b>Electronics</b>			<b>Data Processing</b>
<i>Market Segmentation</i>	<i>Sensors &amp; Transducers</i>	<i>Optoelectronics &amp; Optics</i>	<i>Passive Devices</i>	<i>Packaging</i>	<i>Active Devices</i>	<i>Magnetic Heads</i>
<b>Devices &amp; Applications</b>	<ul style="list-style-type: none"> <li>• Ultrasound</li> <li>• Electro medicine</li> <li>• Measurement Instruments</li> <li>• Aerospace</li> <li>• Automotive</li> <li>• Solar Cells</li> </ul>	<ul style="list-style-type: none"> <li>• Photo Detectors</li> <li>• Lasers</li> <li>• LED / VLED</li> <li>• Fiber Optic Couplers &amp; Transceivers</li> <li>• Display Panels (LCD, Flat Panels)</li> <li>• Facsimile Scan / Print Heads</li> <li>• Optical Components</li> </ul>	<ul style="list-style-type: none"> <li>• Resistors</li> <li>• Capacitors</li> <li>• Oscillators</li> <li>• Signal Fillers</li> <li>• Communication &amp; Microwave</li> <li>• Thin Film Print Heads</li> </ul>	<ul style="list-style-type: none"> <li>• PCB</li> <li>• PPGA</li> <li>• Chip Carriers</li> <li>• IC Packaging</li> <li>• Hybrid Substrate</li> </ul>	<ul style="list-style-type: none"> <li>• IC's</li> <li>• Transistors</li> <li>• Diodes</li> <li>• Discrete Devices</li> <li>• Power Devices</li> </ul>	<ul style="list-style-type: none"> <li>• Thin Film (disk)</li> <li>• Thick Film (disk)</li> <li>• Tape R/W Heads</li> </ul>
<b>Materials</b>	<ul style="list-style-type: none"> <li>• Piezoelectric</li> <li>• Silicon on sapphire (SOS)</li> <li>• Calcium Tungsten</li> </ul>	<ul style="list-style-type: none"> <li>• Quartz</li> <li>• Germanium</li> <li>• GaAs, Silicon</li> <li>• Sapphire</li> <li>• Glass</li> <li>• Beryllium</li> <li>• Fiber Optic</li> </ul>	<ul style="list-style-type: none"> <li>• Green &amp; Fired Ceramic</li> <li>• Alumina</li> <li>• Quartz</li> <li>• Lithium Niobate</li> <li>• Plastic</li> <li>• Glass</li> </ul>	<ul style="list-style-type: none"> <li>• Green &amp; Fired Ceramic</li> <li>• Alumina</li> <li>• Glass</li> <li>• Fiberglass</li> <li>• Plastic</li> </ul>	<ul style="list-style-type: none"> <li>• Silicon</li> <li>• Gallium Arsenide</li> <li>• Gallium Phosphate</li> <li>• Germanium</li> </ul>	<ul style="list-style-type: none"> <li>• Titanium Carbide (TIC)</li> <li>• Ferrite</li> <li>• Alumina (TIC)</li> </ul>
<b>Market &amp; Process Highlights</b>	<ul style="list-style-type: none"> <li>• Medium Volume</li> <li>• High Quality</li> <li>• High Accuracy</li> <li>• Broad Range of Thickness</li> <li>• Small to Medium Area (&lt;6"X6")</li> <li>• Thin Walls (minimum vibration)</li> <li>• Costly Materials</li> </ul>	<ul style="list-style-type: none"> <li>• Medium/High Volume</li> <li>• High Quality</li> <li>• High Yield</li> <li>• High Accuracy</li> <li>• Broad Range of Thickness &amp; Hardness</li> <li>• Costly Materials</li> </ul>	<ul style="list-style-type: none"> <li>• Medium / High Volume</li> <li>• High Quality</li> <li>• High Yield</li> <li>• Medium / High Accuracy</li> <li>• Broad Range of Thickness &amp; Hardness</li> </ul>	<ul style="list-style-type: none"> <li>• Medium / High Volume</li> <li>• High Quality</li> <li>• High Yield</li> <li>• Large Substrate Area (14"X14")</li> <li>• Range of Thick. &amp; Hardness</li> </ul>	<ul style="list-style-type: none"> <li>• Medium Volume</li> <li>Die separation</li> <li>• Semi-auto Operation</li> <li>• Pilot Line, R&amp;D</li> <li>• High Quality</li> <li>• High Yield</li> </ul>	<ul style="list-style-type: none"> <li>• Medium / High Volume</li> <li>• High Quality</li> <li>• High Yield</li> <li>• High Accuracy</li> <li>• Thin Walls (Minimum Vibration)</li> <li>• Land Definition &amp; Separation</li> </ul>

## Single Diamond Machining Mechanism





## Single Diamond Machining Mechanism





*Blade Seminar*

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# Manufacturing Techniques



*Blade Seminar*

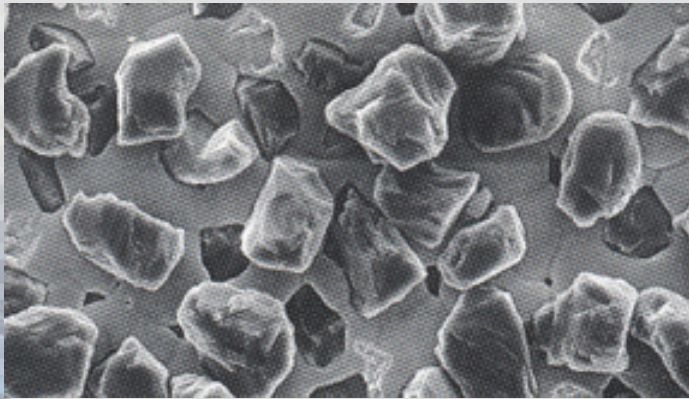
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# Blade Characteristics

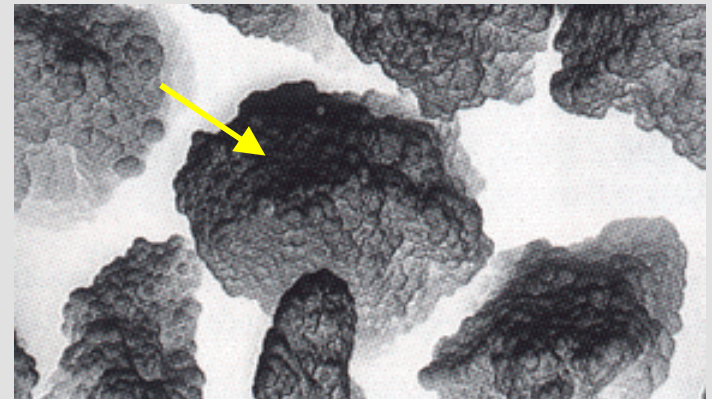




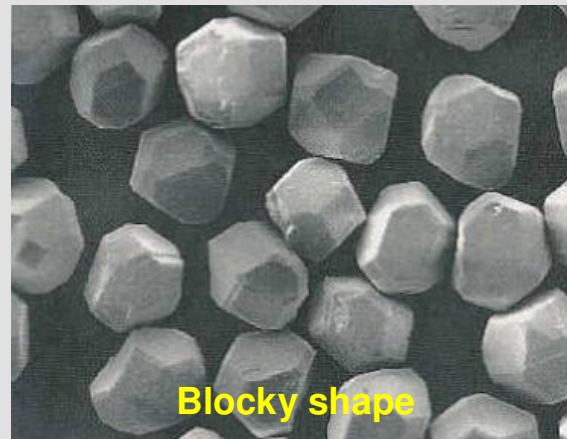
## Diamond Selection in blade Manufacturing



**Strong, blocky single crystal  
used in nickel & m. sintered  
matrices**



**Friable, irregular shape coated  
with nickel alloy used in resin  
matrices**

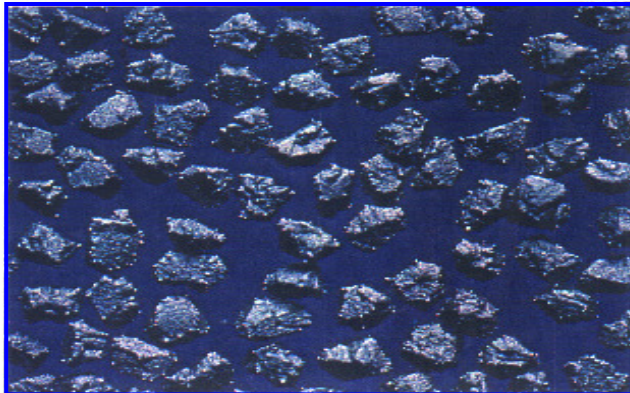
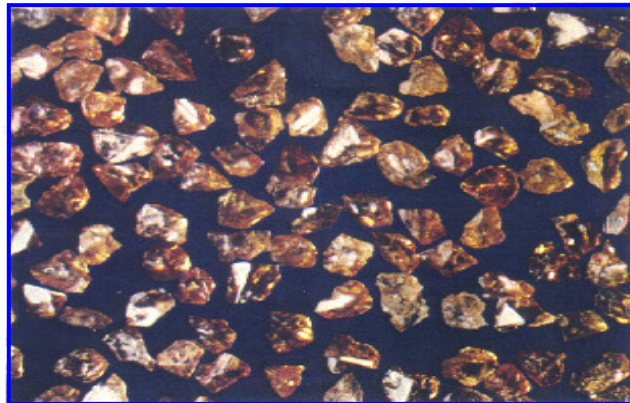


**Blocky shape**



## *Diamond Selection in blade Manufacturing*

**CBN - Cubic Boron Nitride (Borozone)**  
*For Grinding and Cutting Ferrous Materials*





## Standard available Diamonds

### Nickel type blades:

2 - 4mic. , 3 - 6mic., 4 - 8mic., 10mic., 17mic., 30mic., 50mic.

### Resin type blades:

3mic., 6mic. (3000 mesh), 9mic. (1800 mesh), 15mic. (1200 mesh),  
20mic. (1000 mesh), 25mic. (800 mesh), 30mic.(600 mesh),  
35mic.(400 mesh), 45mic. (325 mesh), 53mic. (270 mesh)  
63mic. (230 mesh), 88mic. (170 mesh), 105mic. (140 mesh)

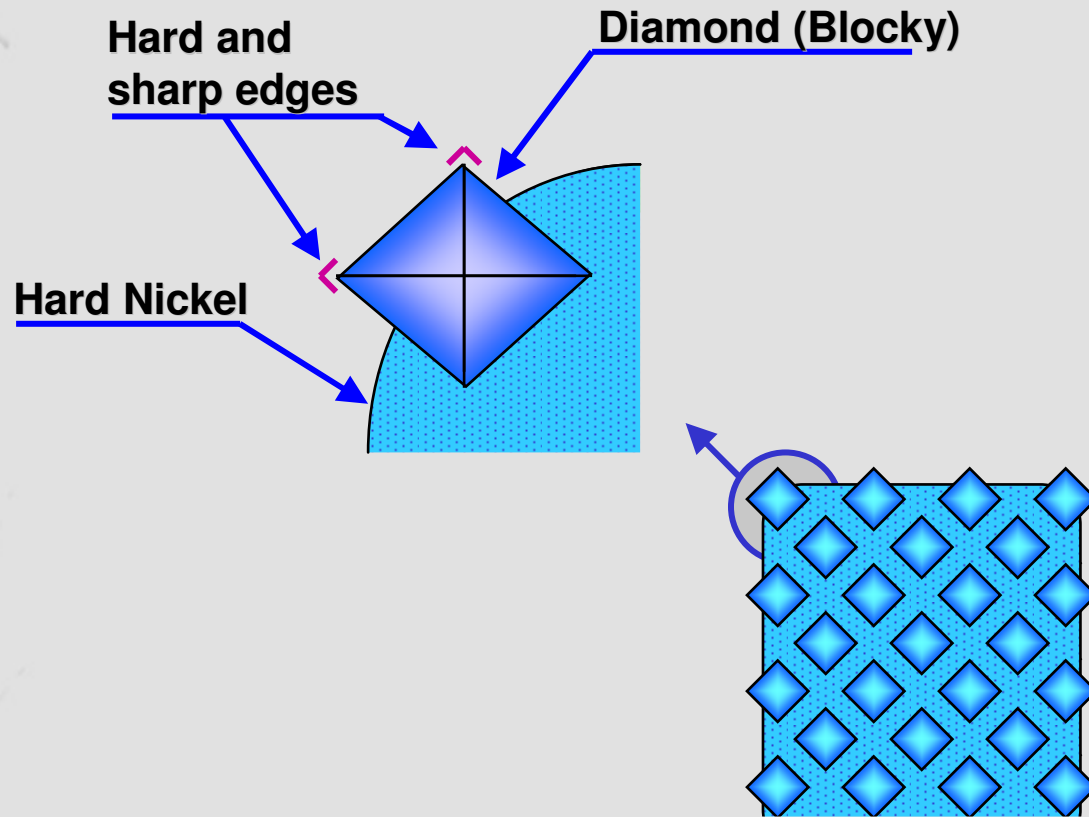
- For special application going up to 200mic.
- Any new diamond grit can be made

### Metal sintered blades:

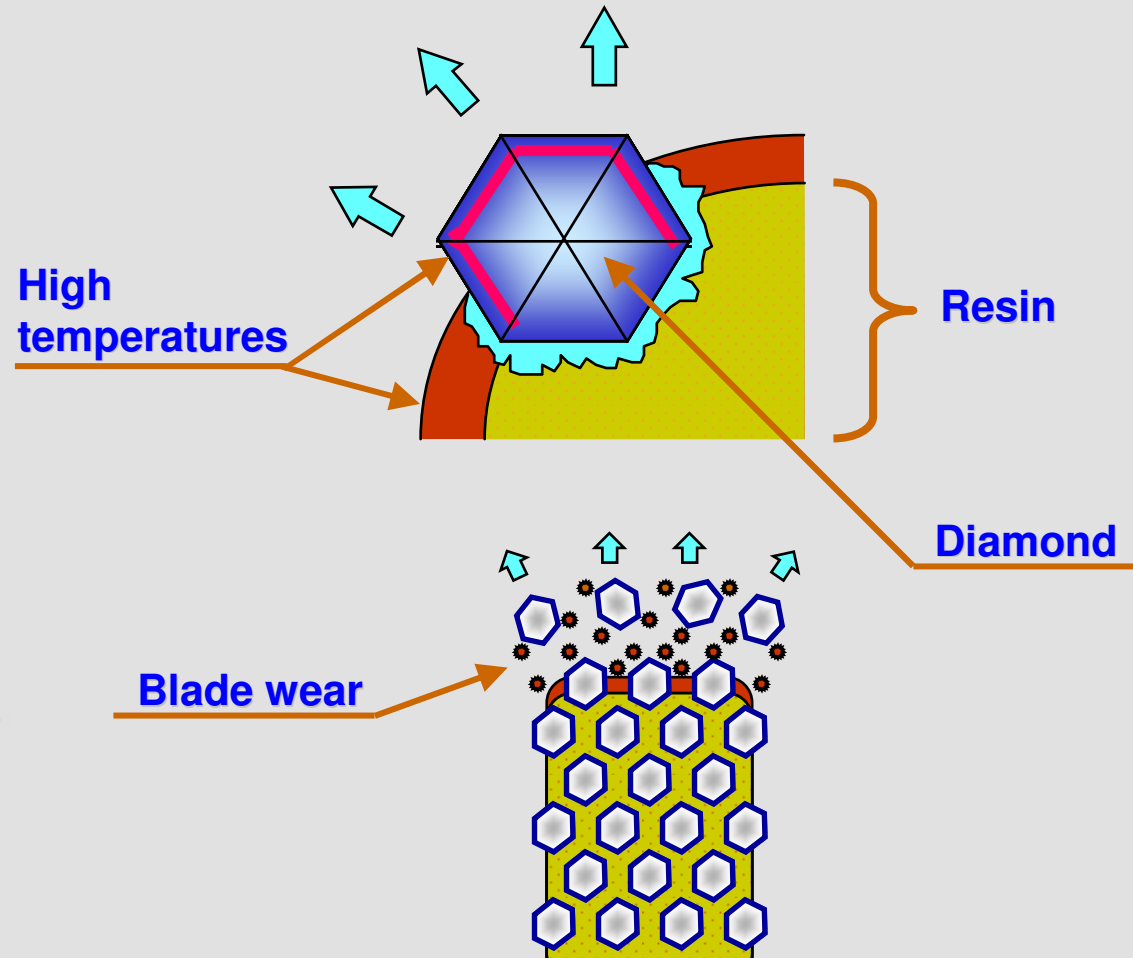
2- 4mic., 3- 6mic., 4- 8mic., 10mic., 17mic., 20mic., 25mic., 30mic.,  
45mic., 50mic., 63mic., 70mic., 80mic.,105mic.,

- Any new diamond grit can be made

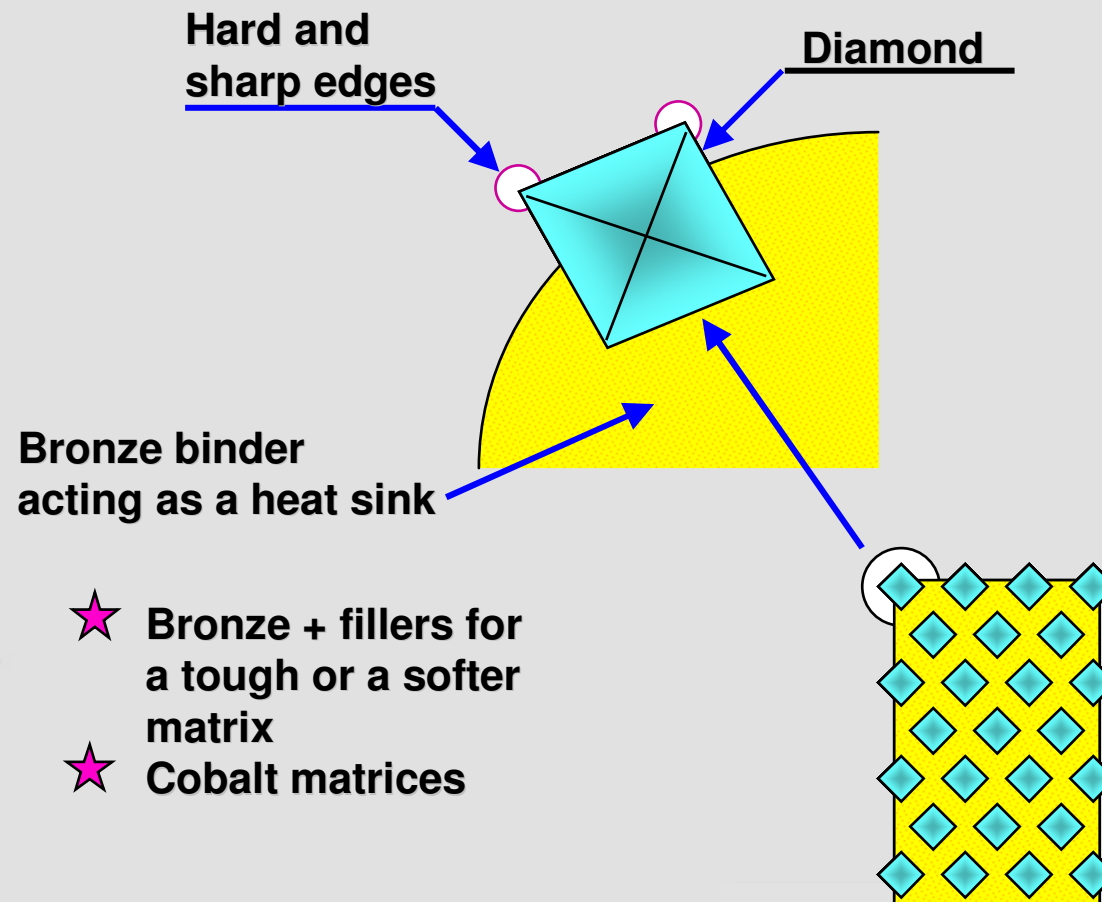
## Nickel Bond - Low Wear blade



# Resin Bond-self re-sharpening and free cutting blade



## Metal Sintered blades



### **Resin**

#### **Advantages:**

- Cuts almost any material
- Clean and chip free cuts on hard and brittle materials
- Thick blades up to .100" are available
- No need for long dressing
- A variety of different resin matrixes is available
- Any new diamond grit can be made at low cost

#### **Disadvantages:**

- Higher blade wear
- The edge geometry is lost sooner
- Relatively lower R.P.M.
- Minimum thickness is .003" depending on diamond grit

## *Advantages & Disadvantages of blade binders*

### **Nickel**

#### **Advantages:**

- Very low blade wear (Some time it is a disadvantage)
- Maintaining the edge geometry
- Very good on accurate applications (Magnetic heads)
- Very thin blades can be made - .0006" (0.0152mm)

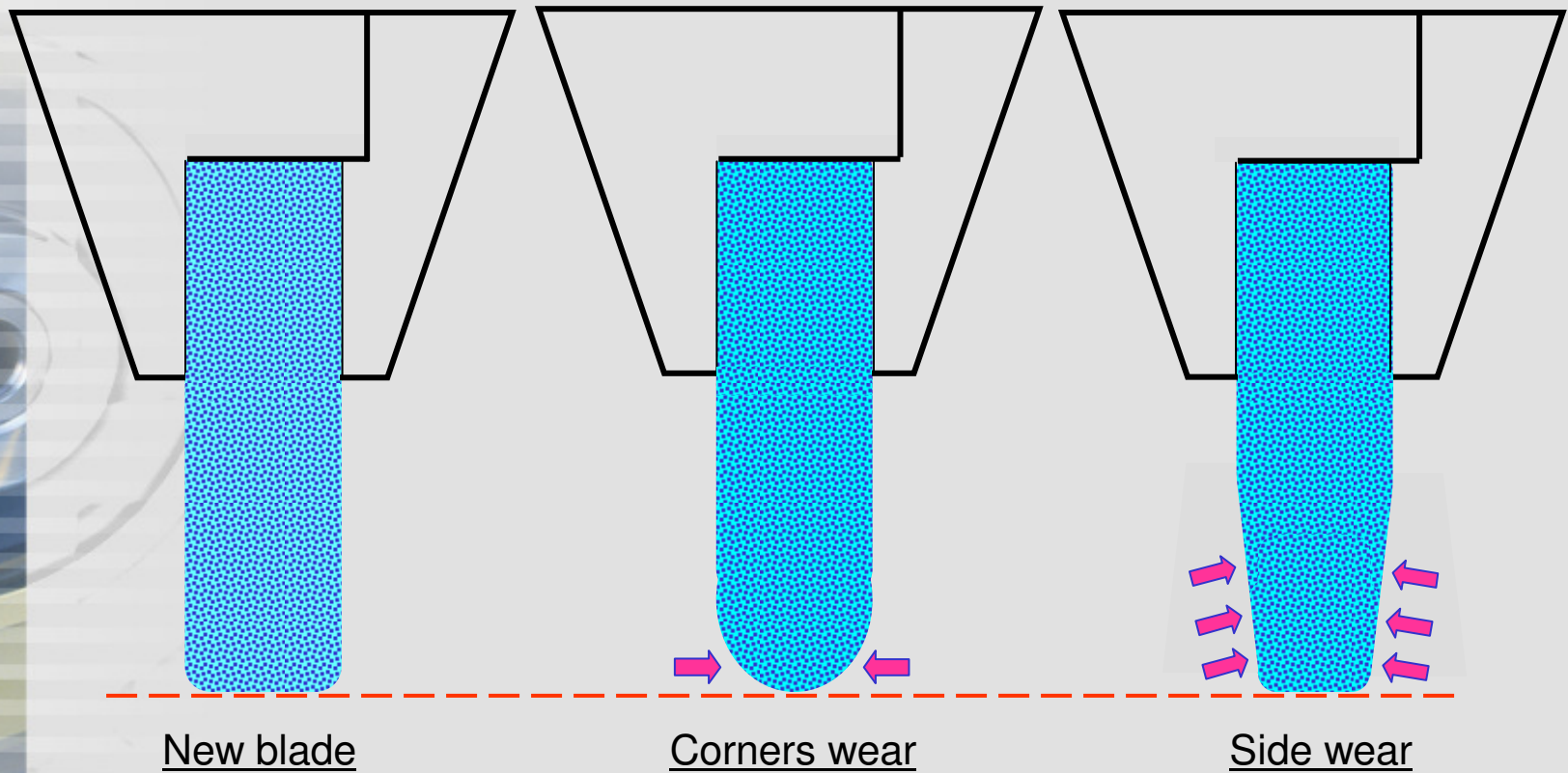
#### **Disadvantages:**

- Max thickness .018" - .020" (0.45 - 0.50mm)  
(Can go thicker with Steel Core blades)
- Long dressing procedure
- High cost of new diamond grits (New plating set-up)
- Can not cut very hard and brittle materials (Overloading)
- Side wear on singulation type application due to min. radial wear. (BGA & similar applications)

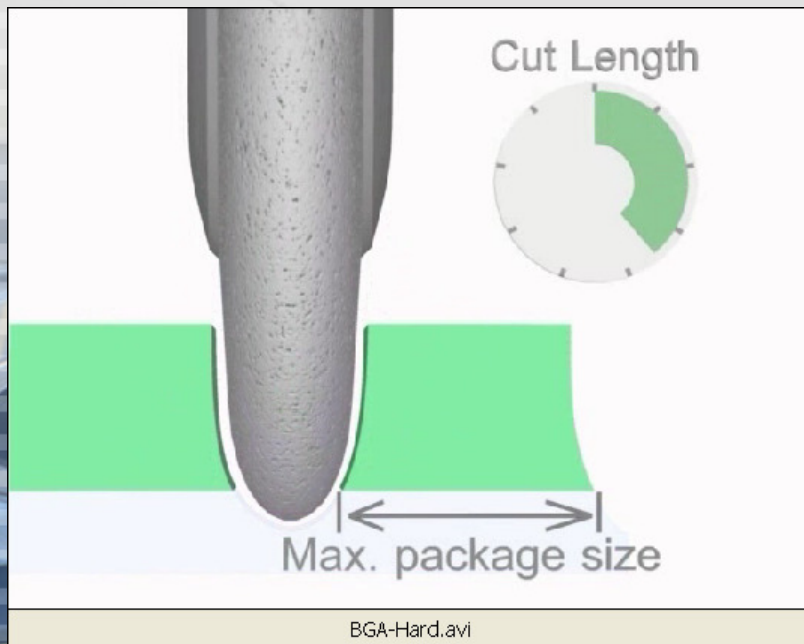


## Advantages & Disadvantages of blade binders

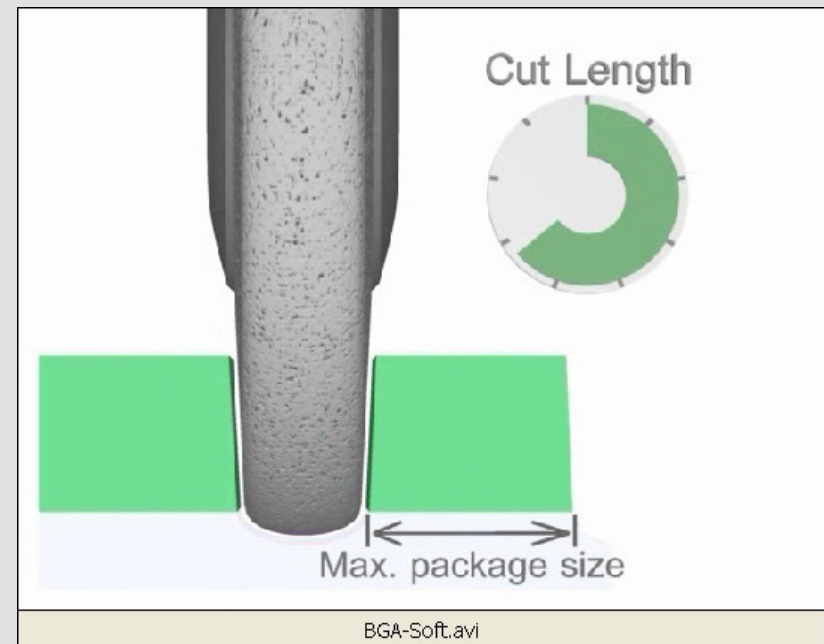
### Nickel



## Advantages & Disadvantages of blade binders



**Hard bond – shorter life**



**Soft bond – longer life**



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## *Advantages & Disadvantages of blade binders*

### **M. Sintered**

#### **Advantages:**

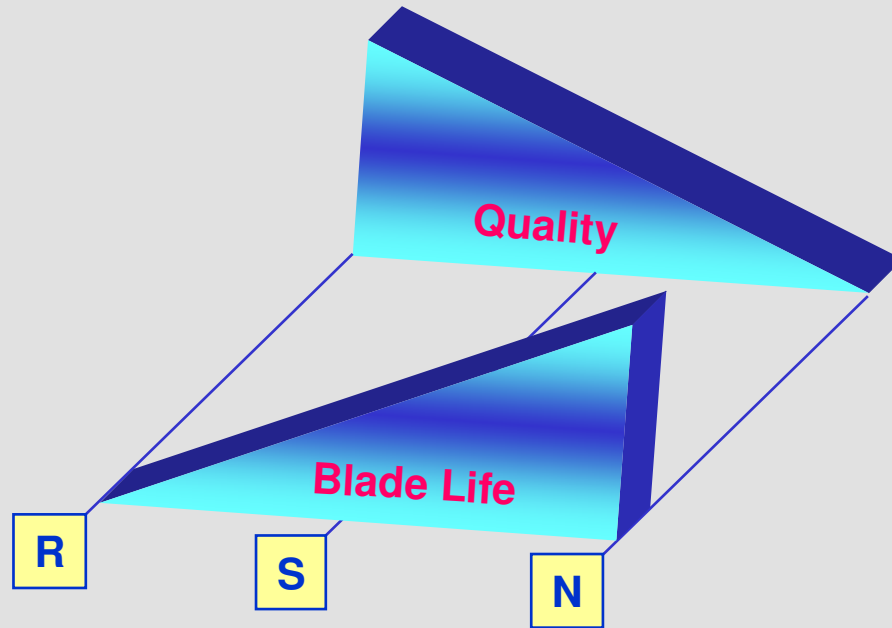
- Lower wear than Resinoid
- Maintaining the edge geometry much longer compare to resin
- Can be lapped to very precise thicknesses
- Very thick blades can be made (Way over .020")
- Stable matrix (Stress free)
- Many different matrices can be made (Softer or harder)
- Any new diamond grit can be made at low cost

#### **Disadvantages:**

- Longer dressing compare to Resinoid
- Minimum thickness limitations (New thin product is developed down to 0.030mm)
- Relatively lower R.P.M.



## Blade Matrix Characteristics

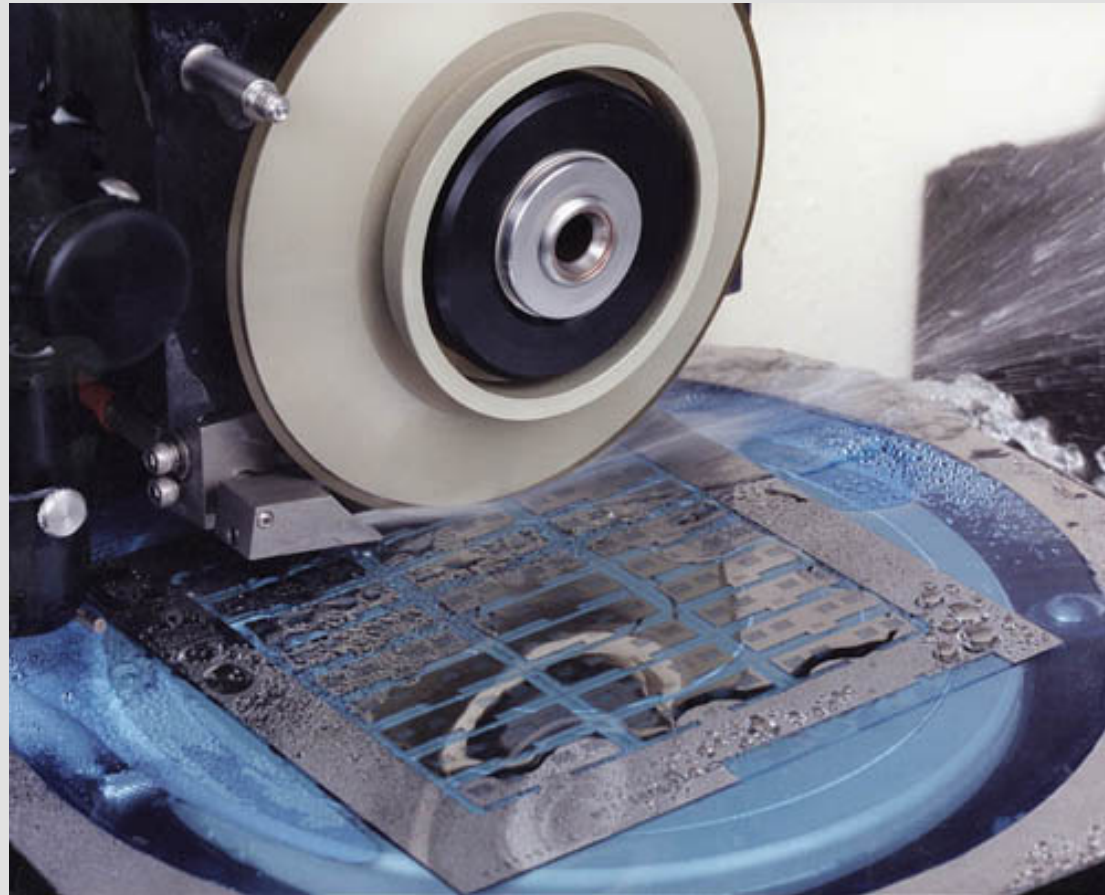




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## *Blade Characteristics*

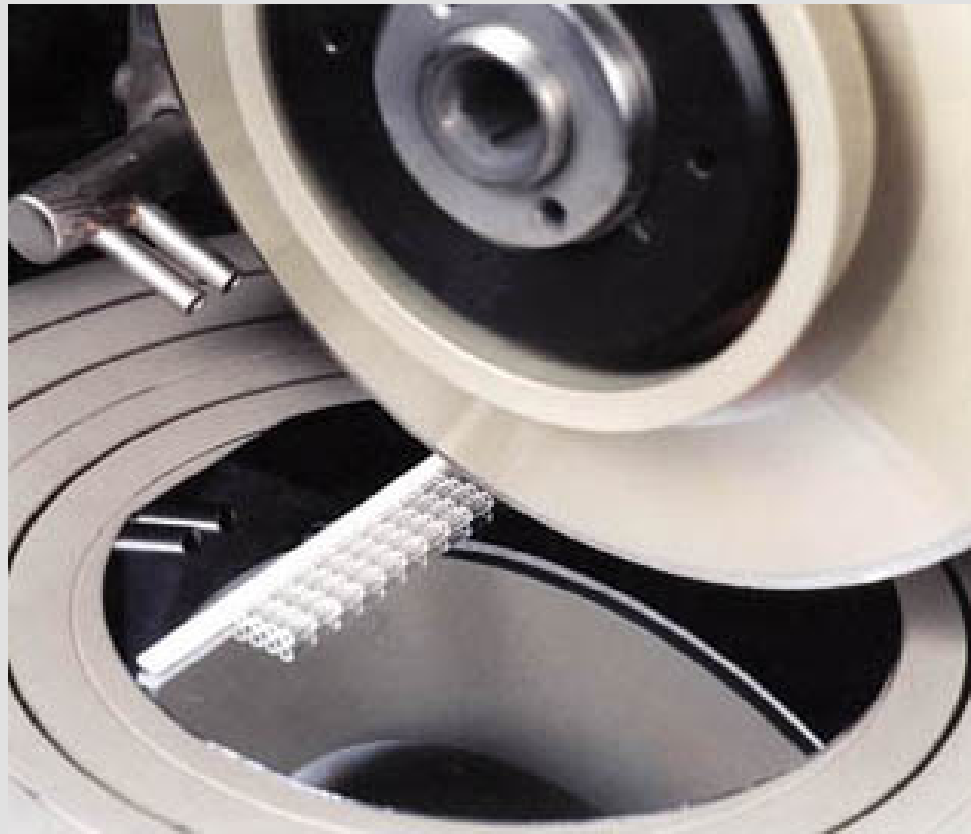
**.025" thick Glass Plate diced with Resinoid blade**





## *Blade Characteristics*

**Glass Tubes diced with resinoid Blade**





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## *Blade Characteristics*

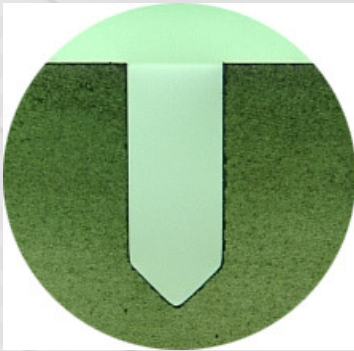
**.025" thick Hard Al. (99.6%) diced with Resinoid Blade**



*.025 Thick Hard Al (99.6%) Diced  
with Resinoid Blade*

## Blade Geometry

**Angled cut**



**Special edge geometry's (By grinding)**



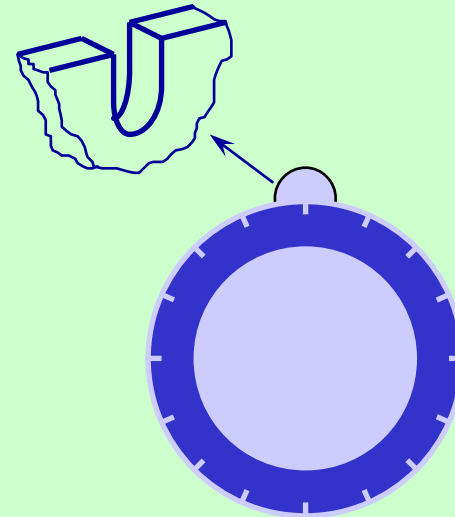
### Nickel & Metal Sintered

#### Examples:

4.256" O.D. x 54 Slots  
4.600" O.D. x 60 Slots  
4.600" O.D. x 16 Slots  
4.600" O.D. x 8 Slots

2.188" & 2.250" O.D. x 72 Slots  
2.188" & 2.250" O.D. x 16 Slots  
2.188" & 2.250" O.D. x 8 Slots

Other O.D. blades x different Slot geometry's  
are available



**Resinoid blades can also be made with Slots**

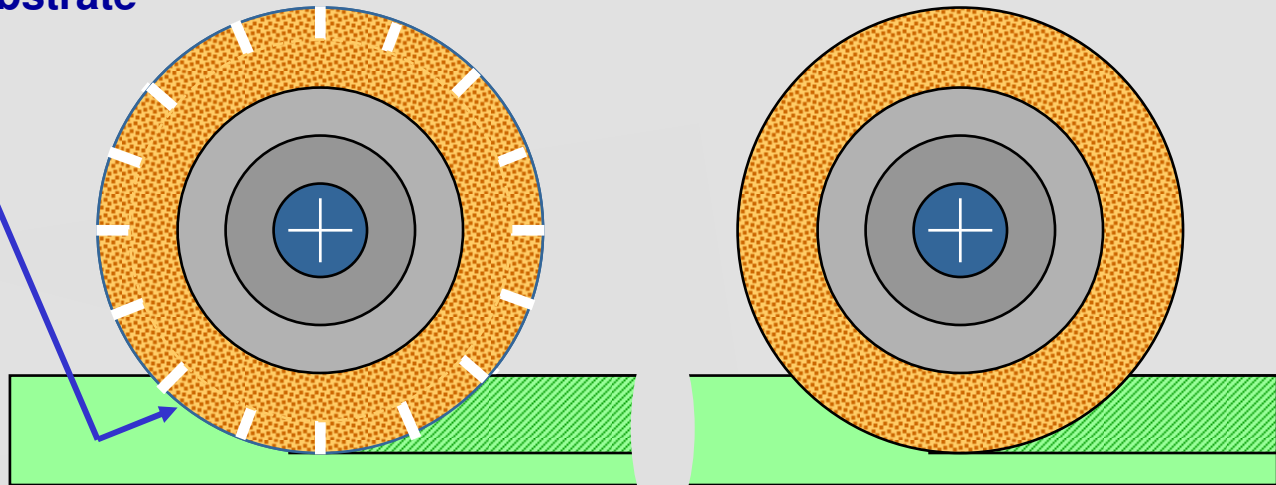
## Serrated Blades

**Advantages:**

- ★ **Less contact between the edge and the substrate**



**Less load during the dicing**

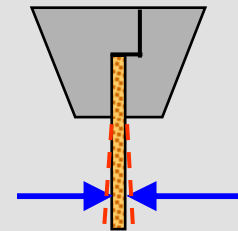


- ★ **Better Coolant**



**Longer life**

- ★ **Disadvantages:  
Wider kerf**





## *Blade Characteristics*

**.5" Thick Optical prism diced with a Resinoid Blade**

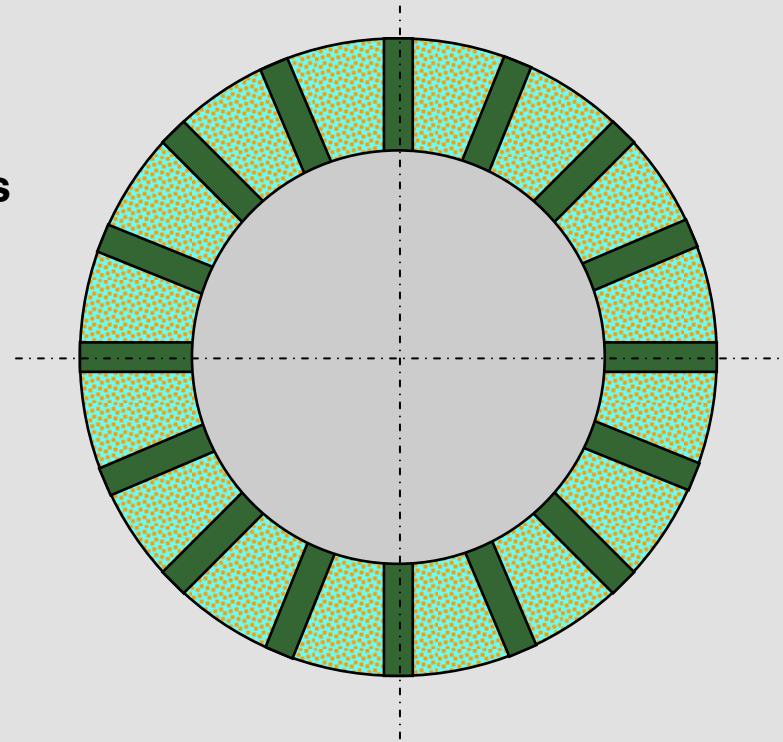
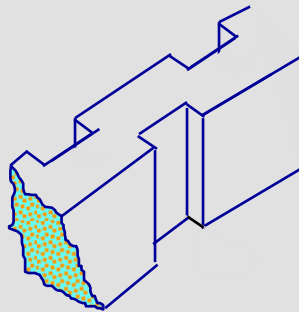


*Optical Prism Diced with a Resinoid Blade*

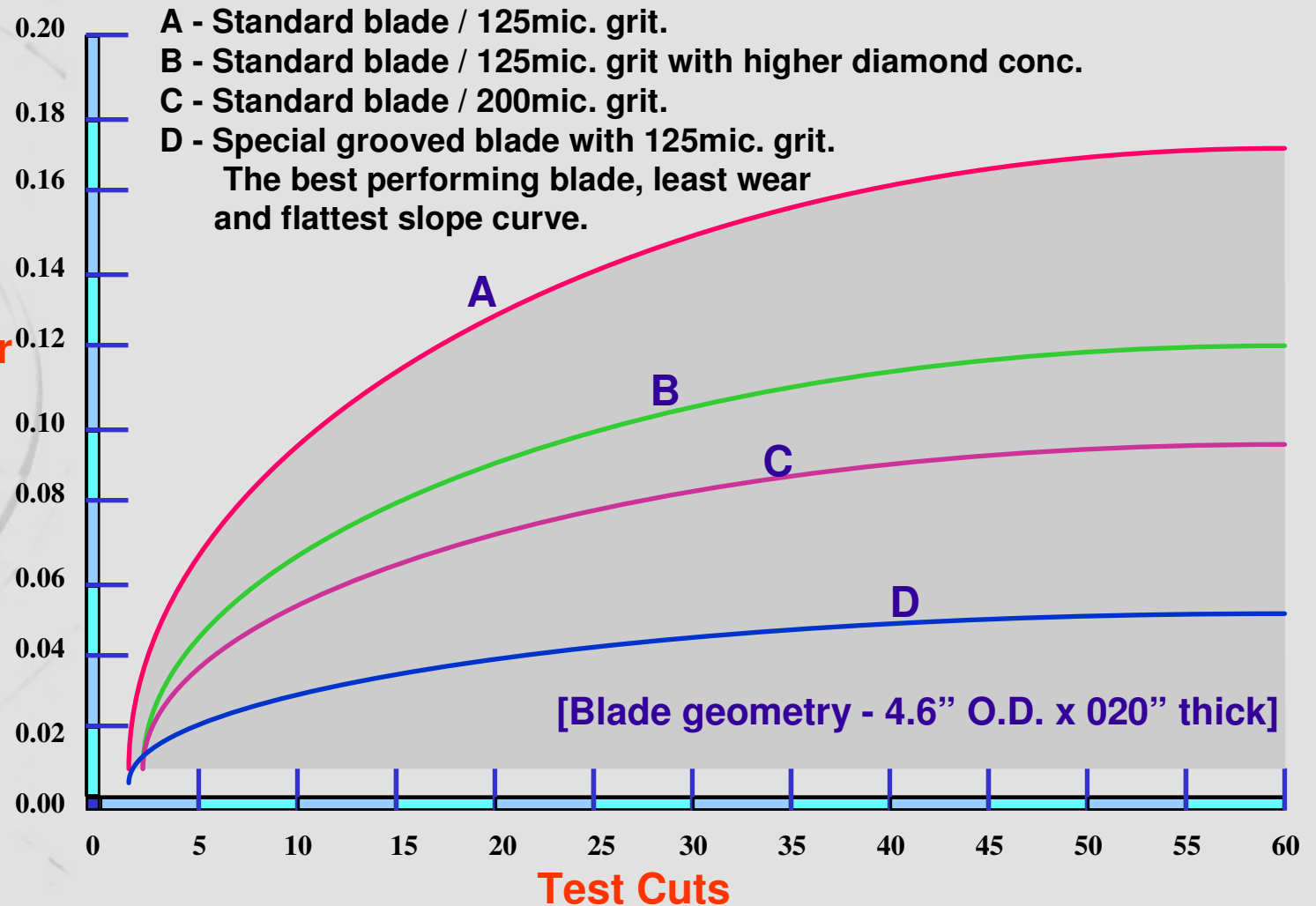


## *Special Grooved Blade - SPG*

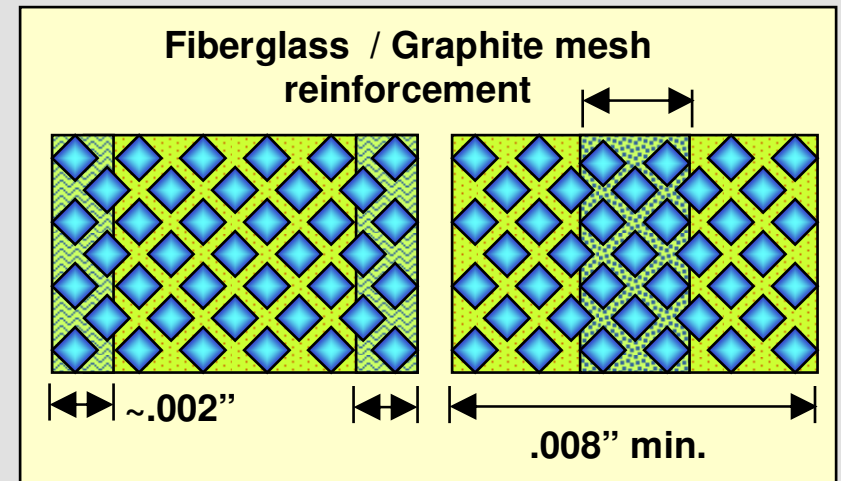
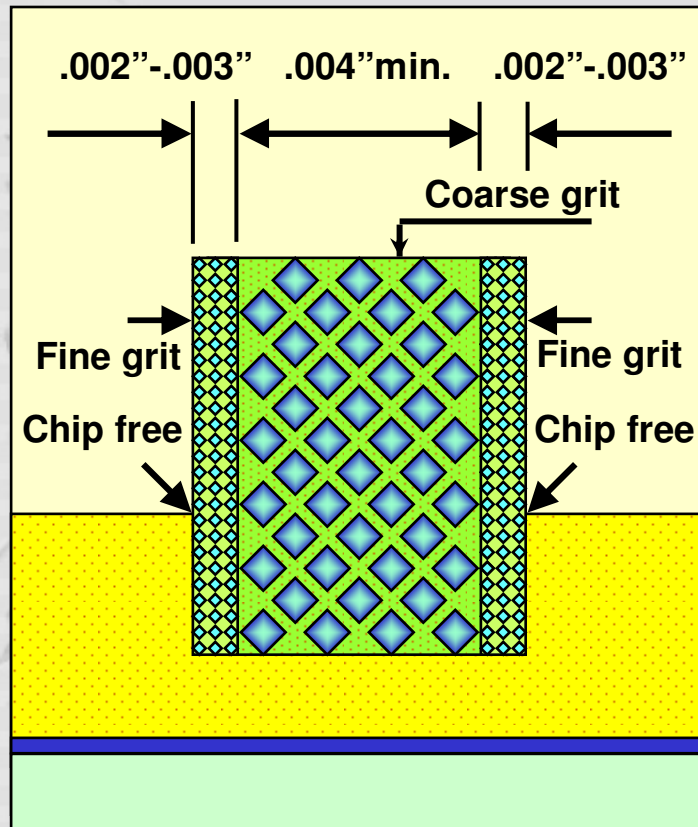
- **Minimizes load and blade wear during the dicing process**
- **Min. thickness .012"**
- **Can be used with a high cooling flange set or with standard flanges**



## Wear Comparison Between Standard & SPG blades



## Diamond Combination & Reinforcement in Resin Blades



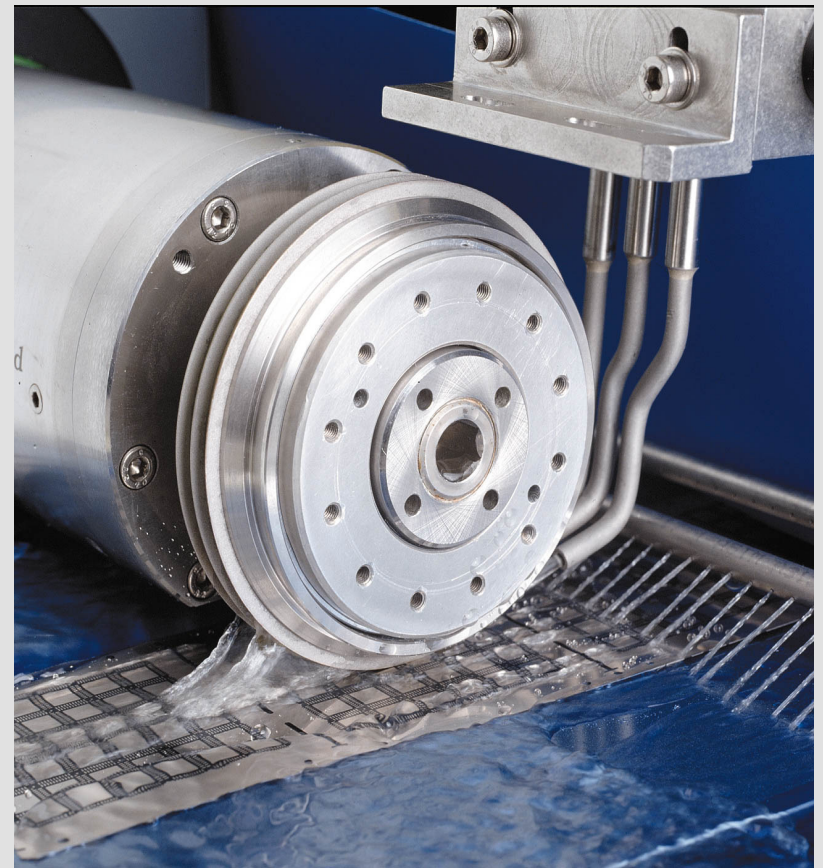


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## *E Series*

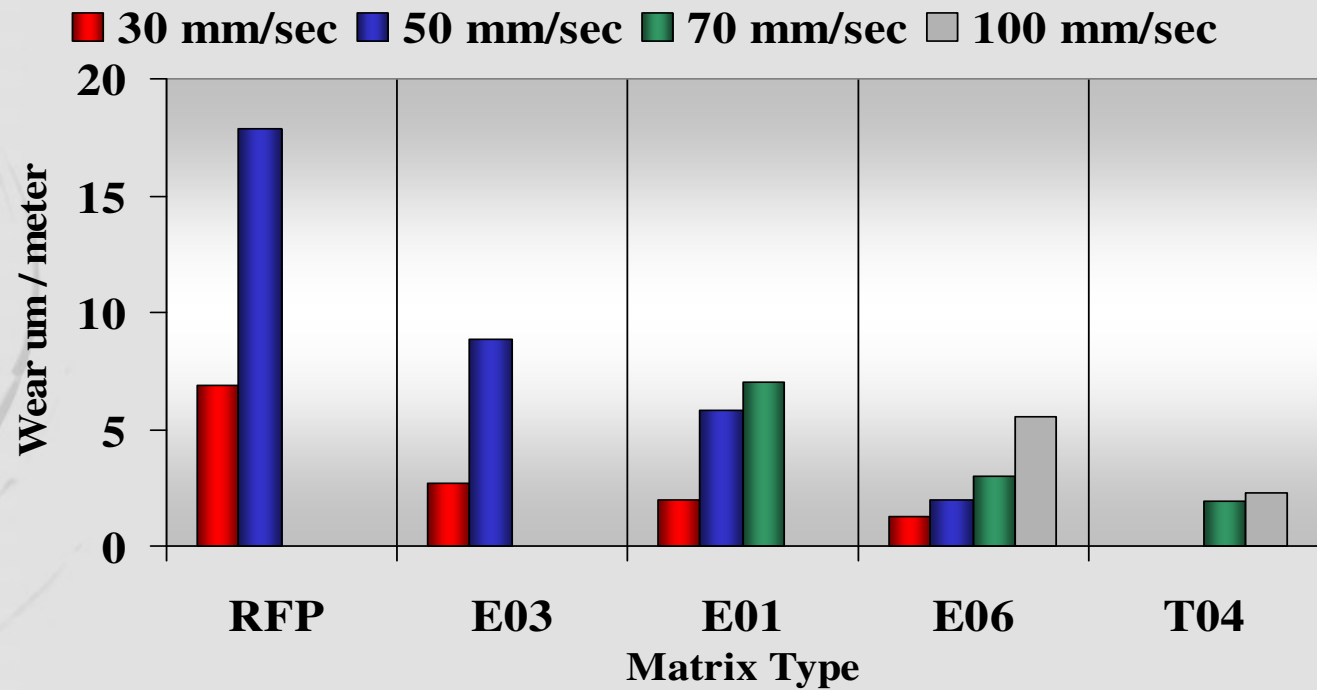
### *Extended Life Resin Blades for QFN*

- **Low cost versus cut length ration**
- **Blade life up to ten times longer than standard resins**
- **Optimized to provide excellent cut quality for the most severe dicing challenges**



More meters of dicing at 100mm/sec

### QFN Application

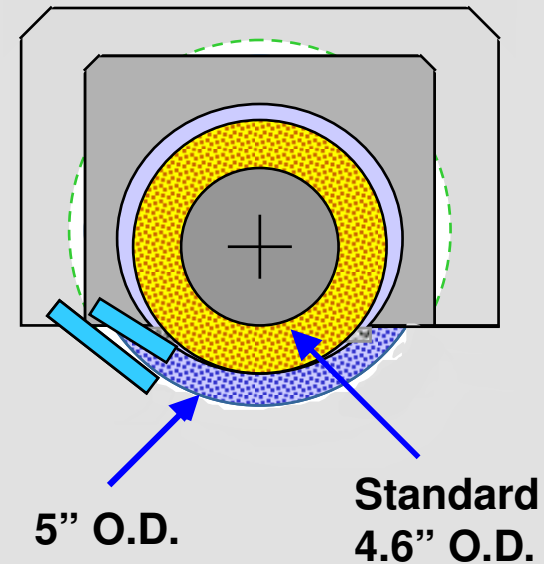




**Designed for thick substrates where a large exposure is needed**

**Blades available:**

- **Nickel serrated**- 5.0" O.D. x 3.5" I.D.  
5.0" O.D. x 3.0" I.D.
- **Resinoid** - 5.0" O.D. x 3.5" I.D.  
5.0" O.D. x 3.0" I.D.
- **M. Sintered** - 5.0" O.D. x 3.5" I.D.  
5.0" O.D. x 3.0" I.D.

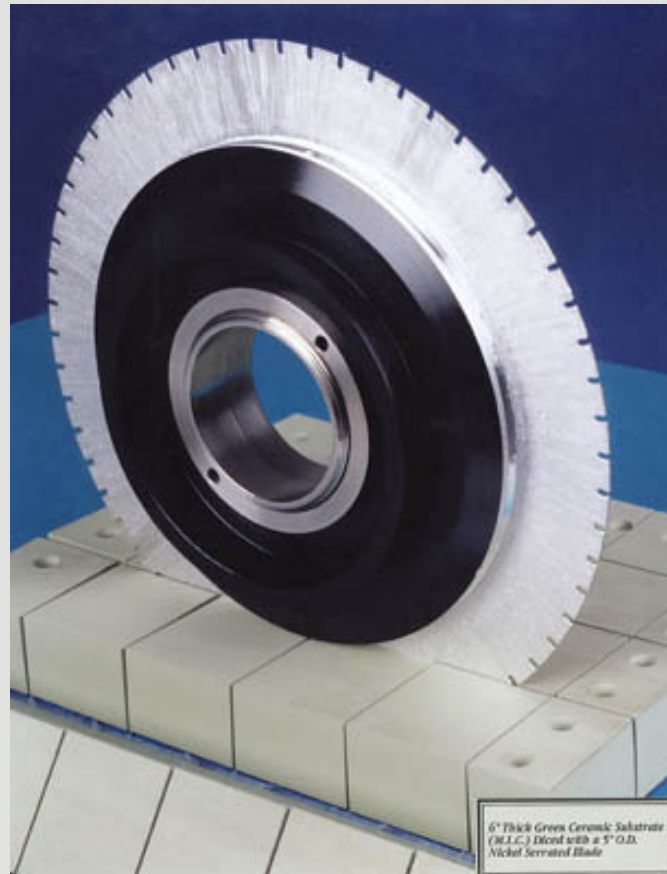




## *Blade Characteristics*

### **Green Ceramic diced with Nickel Serrated blade**

**.6" thick substrate  
(M.L.C.) diced with  
a 5" Nickel serrated  
blade**

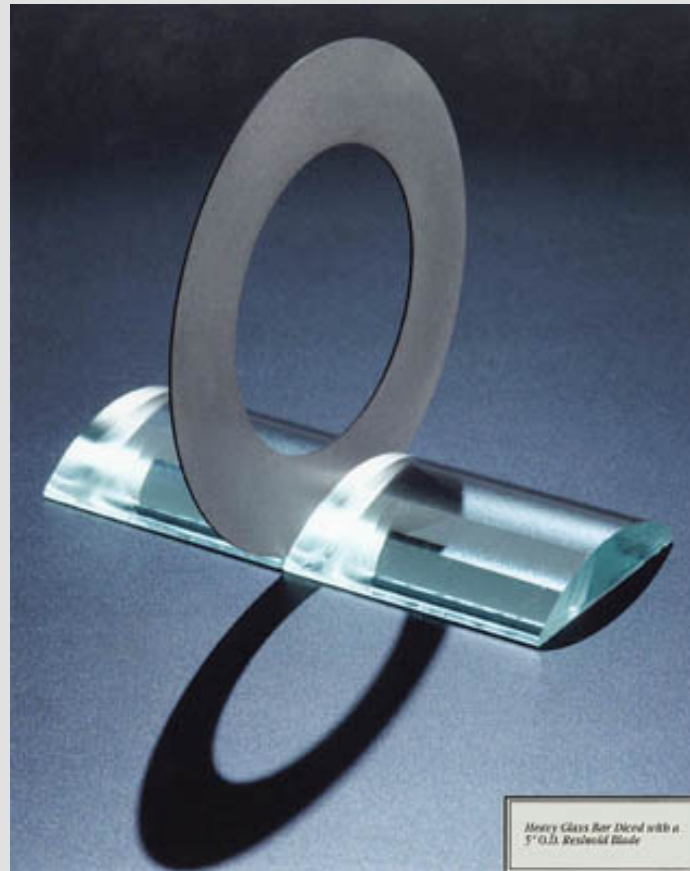




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## *Blade Characteristics*

**Heavy Glass bar diced with 5" Resinoid blade**



Heavy Glass Bar Diced with a  
5" O.D. Resinoid Blade



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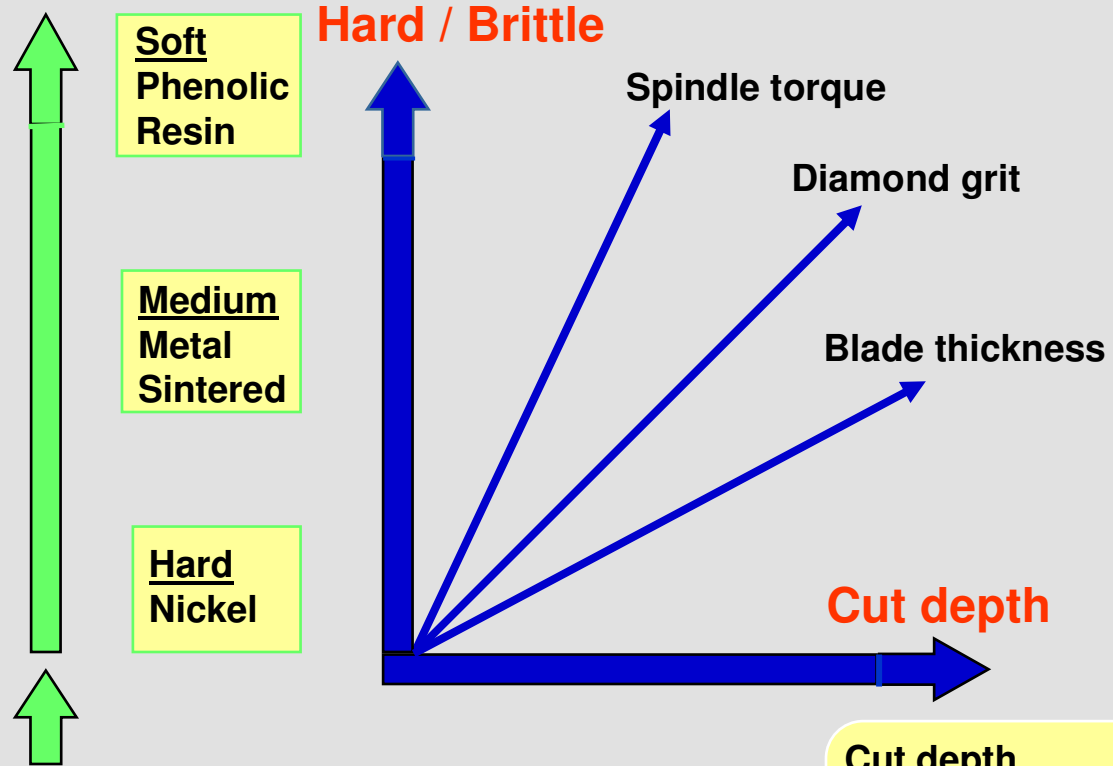
## *Blade Characteristics*

**1/2" Ceramic tube diced with 5" Resinoid blade**

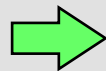


*1/2" Ceramic Tube Diced with a  
5" O.D. Resinoid Blade*

## The Effect of Blade & Dicing Parameters on Cut Quality & Throughput



- Cut quality
- Throughput
- Blade wear



Blade & Process Parameters



- Cut depth
- Feed rate
- Spindle RPM
- Blade thickness
- Diamond grit / %
- Blade exposure



*Dicing Seminar*

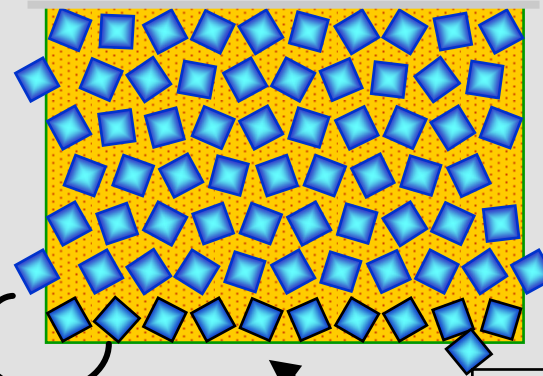
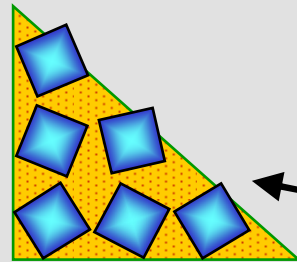
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# Dressing

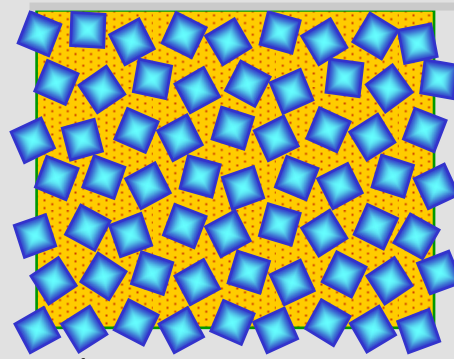
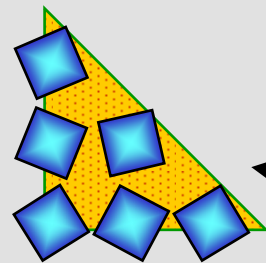


## Nickel Bond Dressing

**Before dressing**  
Diamonds are not exposed



**Blade edge**



**Blade edge after dressing**